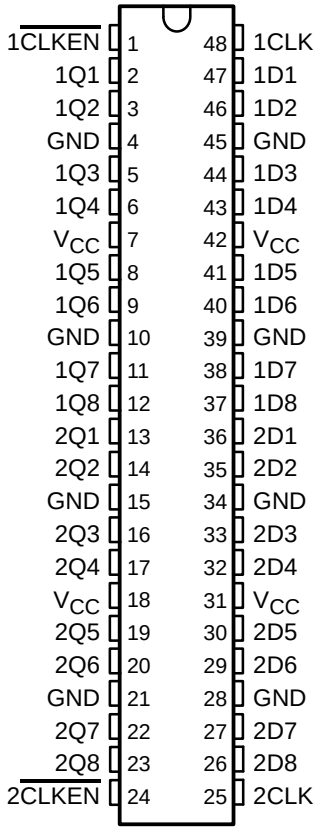
- **Members of the Texas Instruments *Widebus*™ Family**
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17**
- **Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 5 V, T_A = 25°C**
- **Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise**
- **Flow-Through Architecture Optimizes PCB Layout**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Packaged in Plastic 300-mil Shrink Small-Outline Packages and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Spacings**

SN54ABT16377 . . . WD PACKAGE
SN74ABT16377 . . . DL PACKAGE
(TOP VIEW)



description

The ′ABT16377 is a 16-bit positive-edge-triggered D-type flip-flop with a clock (1CLK or 2CLK) input. It is particularly suitable for implementing buffer and storage registers, shift registers, and pattern generators.

The device can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock input, the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

Data input information that meets the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock pulse if the common clock-enable ($1\overline{CLKEN}$ or $2\overline{CLKEN}$) input is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When the buffered clock input is at either the high or low level, the D input signal has no effect at the output. The circuits are designed to prevent false clocking by transitions at $\overline{CLKEN}$.

The SN74ABT16377 is available in TI's shrink small-outline package (DL), which provides twice the I/O pin count and functionality of standard small-outline packages in the same printed-circuit-board area.

The SN54ABT16377 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16377 is characterized for operation from –40°C to 85°C.

PRODUCT PREVIEW

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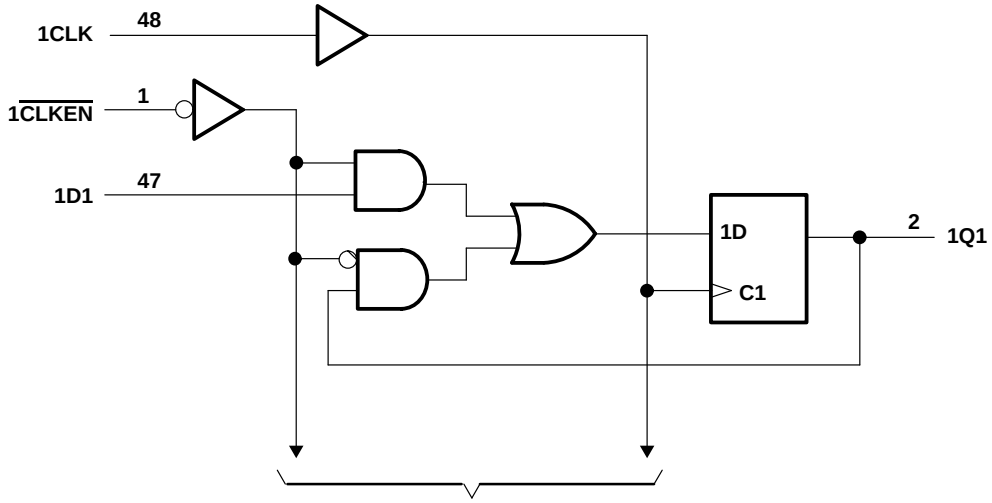
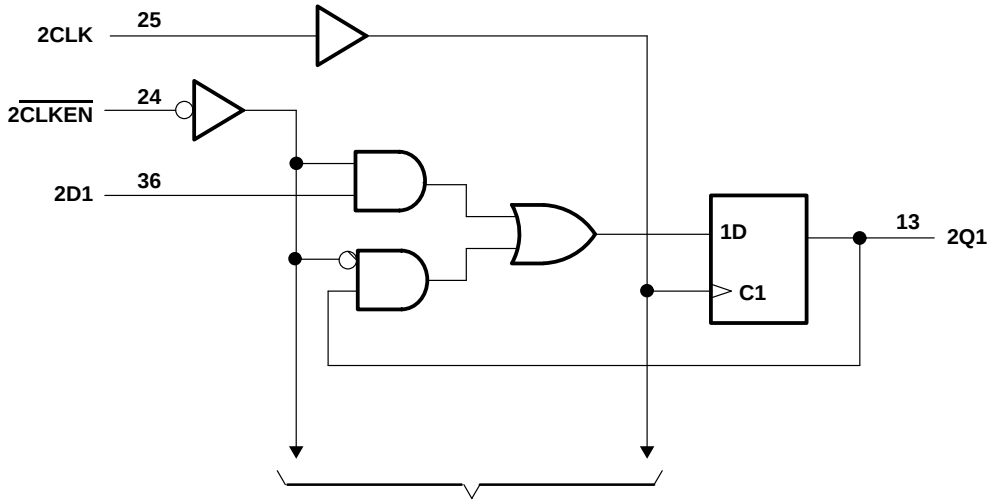
FUNCTION TABLE
(each flip-flop)

INPUTS			OUTPUT
$\overline{\text{CLKEN}}$	CLK	D	Q
H	X	X	Q_0
L	↑	H	H
L	↑	L	L
X	H or L	X	Q_0

logic diagram (positive logic)





PRODUCT PREVIEW

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, V_O . . . . . –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT16377 . . . . . 96 mA
SN74ABT16377 . . . . . 128 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air) . . . . . 0.85 W
Storage temperature range . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 2)

		SN54ABT16377		SN74ABT16377		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
V_I	Input voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current		–24		–32	mA
I_{OL}	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10	ns/V
T_A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 2: Unused or floating inputs must be held high or low.

PRODUCT PREVIEW

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		T_A = 25°C			SN54ABT16377		SN74ABT16377		UNIT
			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}	V_{CC} = 4.5 V, I_I = –18 mA				–1.2		–1.2		–1.2	V
V_{OH}	V_{CC} = 4.5 V, I_{OH} = – 3 mA		2.5			2.5		2.5		V
	V_{CC} = 5 V, I_{OH} = – 3 mA		3			3		3		
	V_{CC} = 4.5 V, I_{OH} = –24 mA		2			2				
	V_{CC} = 4.5 V, I_{OH} = – 32 mA		2‡					2		
V_{OL}	V_{CC} = 4.5 V, I_{OL} = 48 mA				0.55		0.55			V
	V_{CC} = 4.5 V, I_{OL} = 64 mA				0.55‡				0.55	
I_I	V_{CC} = 5.5 V, V_I = V_{CC} or GND				±1		±1		±1	µA
I_{off}	V_{CC} = 0, V_I or V_O ≤ 4.5 V				±100				±100	µA
I_{CEX}	V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O§	V_{CC} = 5.5 V, V_O = 2.5 V		–50	–100	–180	–50	–180	–50	–180	mA
I_{CC}	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high			2		2		2	mA
		Outputs low			67		67		67	
		Outputs disabled			2		2		2	
ΔI_{CC}¶	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	V_I = 2.5 V or 0.5 V									pF
C_o	V_O = 2.5 V or 0.5 V									pF

† All typical values are at V_{CC} = 5 V.
‡ On products compliant to MIL-STD-883, Class B, this parameter does not apply.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
¶ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

PRODUCT PREVIEW

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